OIPE JC147
MAY 16 2001
PATENT & TRADEMARK OFFICE

05-23-2001

101726469

FORM PTO-1596
1-31-92

RECORDA

S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

Docket No.: 50212-190

PATENTS ONLY

To the Honorable Commissioner for Patents and Trademarks: Please record the attached original documents or copy thereto:

1. Name of Conveying Party(ies):
Shinji OGAWA, Hidetoshi ISHIDA, Toshiaki KAKII, Atsushi TAKAI, Atsushi MIURA, and Hiroaki FURUICHI

MLD 5-16-01

Additional name(s) of conveying party(ies) attached? ☐ Yes

2. Name and address of receiving party(ies):
Name: SUMITOMO ELECTRIC INDUSTRIES, LTD.

Address:
5-33, Kitahama 4-chome
Chuo-ku, Osaka-shi
Osaka 541-0041 JAPAN

Additional name(s) & address(es) attached? ☐ Yes

3. Nature of Conveyance:

☒ Assignment
☐ Merger
☐ Security Agreement
☐ Change of Name
☐ Other

Execution Date: April 29, April 29, April 27, May 8, May 9, and May 8, 2001 respectively

4. Application number(s) or patent number(s):
If the document is being filed together with a new application, the execution date of the application is:

A. Patent Application No(s).
09/762,094, filed February 2, 2001

B. Patent No(s).

Additional numbers attached? ☐ Yes

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: MCDERMOTT, WILL & EMERY
Internal Address:
Street Address: 600 13th Street, N.W.
City: Washington State: DC Zip: 20005

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41) $40.00
☐ Enclosed
☒ Authorized to be charged to deposit account

8. Deposit account number:
500417

40E

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9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Stephen A. Becker, 26,527
Name and Registration No. of Person Signing

Signature

May 16, 2001
Date

Total number of pages comprising cover sheet: 1

CMB No. 0851-0011 (exp. 4/94)

05/22/2001 DBYRNE 00000061 500417 09762094
01 FC:581 40.00 CH

For Non-U.S. Clients

ASSIGNMENT

Whereas, I/we,

	Name	Address
1)	**Shinji OGAWA**	c/o Yokohama Works of Sumitomo Electric Industries, Ltd., 1, Taya-cho, Sakae-ku, Yokohama-shi, Kanagawa 244-8588 Japan
2)	**Hidetoshi ISHIDA**	c/o Yokohama Works of Sumitomo Electric Industries, Ltd., 1, Taya-cho, Sakae-ku, Yokohama-shi, Kanagawa 244-8588 Japan
3)	**Toshiaki KAKII**	c/o Yokohama Works of Sumitomo Electric Industries, Ltd., 1, Taya-cho, Sakae-ku, Yokohama-shi, Kanagawa 244-8588 Japan
4)	**Atsushi TAKAI**	c/o Telecommunications System Group, HITACHI, LTD., 216, Totsuka-cho, Totsuka-ku, Yokohama-shi, Kanagawa 244-8567 Japan
5)	**Atsushi MIURA**	c/o Telecommunications System Group, HITACHI, LTD., 216, Totsuka-cho, Totsuka-ku, Yokohama-shi, Kanagawa 244-8567 Japan
6)	**Hiroaki FURUICHI**	c/o Production Engineering Research Laboratory, HITACHI, LTD., 292, Yoshida-cho, Totsuka-ku, Yokohama-shi, Kanagawa 244-0817 Japan

hereinafter called assignor(s), have invented certain improvements in

ADAPTER FOR OPTICAL MODULE CONNECTOR, OPTICAL MODULE PRODUCT, AND OPTICAL MODULE MOUNTING SUBSTRATE PRODUCT

and executed an application for Letters Patent of the United States of America therefor on even date herewith unless otherwise indicated below:

filed on February 2, 2001, Serial No. **09/762094**; and

Whereas

SUMITOMO ELECTRIC INDUSTRIES, LTD.
5-33, Kitahama 4-chome, Chuo-ku,
Osaka-shi, Osaka 541-0041 Japan

and, **HITACHI, LTD.**
6, Kanda Surugadai 4-chome,
Chiyoda-ku, Tokyo 101-8010 Japan

(assignee), desires to acquire the entire right, title and interest in the application and invention, and to any United States patents to be obtained therefor;

NOW THEREFORE, be it known that, for good and valuable consideration from assignee, the receipt of which is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

	INVENTORS	DATE SIGNED
1): Name:	Shinji Ogawa **Shinji OGAWA**	April. 29. 2001
2): Name:	Hidetoshi Ishida **Hidetoshi ISHIDA**	April. 29. 2001

(Legalization not required for recording but is prima facie evidence of execution under 35 U.S.C. § 261)

3): Toshiaki Kakii April. 27. 2001
Name: Toshiaki KAKII

4):
Name: Atsushi TAKAI

5):
Name: Atsushi MIURA

6):
Name: Hiroaki FURUICHI

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AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

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1): Name: **Shinji OGAWA**	
2): Name: **Hidetoshi ISHIDA**	

(Legalization not required for recording but is prima facie evidence of execution under 35 U.S.C. § 261)

3):
Name: Toshiaki KAKII

4): Atsushi Takai — May 9, 2001
Name: Atsushi TAKAI

5): Atsushi Miura — May, 9, 2001
Name: Atsushi MIURA

6): Hiroaki Furuichi — May 8, 2001
Name: Hiroaki FURUICHI

(Legalization not required for recording but is prima facie evidence of execution under 35 U.S.C. § 261)